

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1042	257/759-760.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/24 13:48
L2	3981	257/758,762.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/24 13:51
L3	1571	257/763,765.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/24 14:06
L4	2144	257/774.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/24 14:06
S1	1	("6037668").PN.	USPAT	OR	OFF	2004/11/27 13:13
S2	1	conductive adj1 plug and reinforcing adj1 plug and insulating adj1 film	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/27 13:14
S3	1	conductive adj1 plug and reinforcing adj1 plug	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/27 13:14
S4	3	conductive adj1 plug and reinforcing adj1 material	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/27 13:16
S5	259	257/747.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/27 13:24
S6	8	(("4888247") or ("5077115") or ("5358775") or ("5487218") or ("5552210") or ("5574630") or ("6147009") or ("6368967")).PN.	USPAT	OR	OFF	2004/11/27 13:36

S7	55	young near2 modulus and low-k adj1 dielectric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/27 13:47
S8	794	young near2 modulus and organic adj1 material\$2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/27 13:47
S9	106	S8 and polyimides	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/27 13:51
S10	72	S8 and plug	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/27 14:02
S11	1	("6559548").PN.	USPAT	OR	OFF	2004/11/27 13:55
S12	2970	257/758.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/27 14:09
S13	2	conductive adj1 plug and heat adj1 stress	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/27 14:10
S14	114	insulating adj1 film and heat adj1 stress	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/27 14:11
S15	15	S14 and plug	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/27 14:12
S16	58	S14 and wiring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/27 14:13
S17	2281	257/750,751.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/27 14:14

S18	436	257/736,747.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/29 07:25
S19	638	257/736,759.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/29 07:35
S20	708	257/760.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/29 07:41
S21	114	heat adj1 stress and insulating adj1 film	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/29 07:41
S22	159	heat adj1 stress and insulating adj1 layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/29 07:44
S23	15749	stress and insulating adj1 layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/29 07:44
S24	1753	S23 and plug	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/29 07:45
S25	721	S24 and wiring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/29 07:45
S26	332	S25 and "257"/\$\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/29 07:55
S27	2276	257/762,763,765.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/29 08:56

S28	2030	257/774.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/29 08:56
S29	2773	257/736,747,750,751.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/24 13:45